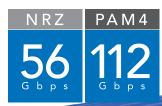
SI-FLY LP 112 Gbps PAM4, LOW PROFILE HIGH-DENSITY CABLE SYSTEM



FEATURES & BENEFITS

- Ultra low profile interconnect for placement adjacent to the IC package, under heat sinks or other cooling hardware
- Up to 16 pairs in an incredibly low 4 mm profile
- 112 Gbps PAM4 per lane enabling 25.6 TB aggregate with a path to 51.2 TB
- Si-Fly[®] HD is the highest density on-package system with 224 Gbps PAM4 performance, routing signals from the silicon package through Eye Speed[®] AIR[™] ultra performance twinax cable (HPC/HPI). Contact HDR@samtec.com for additional information.

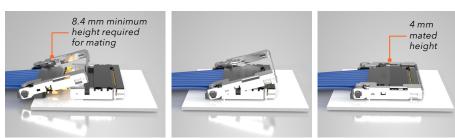
Current

Future

• PCIe[®] 6.0/CXL[®] 3.1 capable

Si-Fly[®] HD features 64 pairs in an incredibly small 14 mm x 14 mm footprint





In development: Rugged latching configuration provides a secure connection directly adjacent to the IC package for increased signal integrity performance

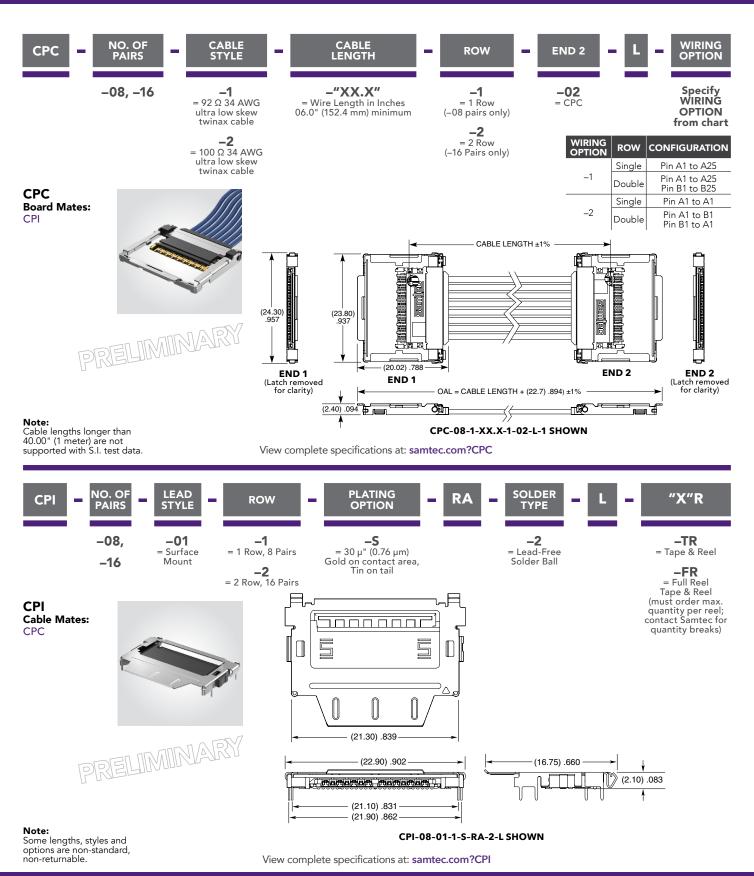
KEY SPECIFICATIONS (CPC/CPI)

CABLE	SIGNAL ROUTING	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING
34 AWG ultra low skew twinax	92 Ω & 100 Ω	Black LCP	Copper Alloy	Au over 50 μ" (1.27 μm) Ni
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Unless otherwise approved in writing by Samtec, all parts and components are designed and built according to Samtec's specifications which are subject to change without notice.



0.6 mm LOW PROFILE CABLE & INTERCONNECT



samtec.com/Si-Fly

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